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AMETEK®
ENGINEERED INTERCONNECT AND PACKAGING

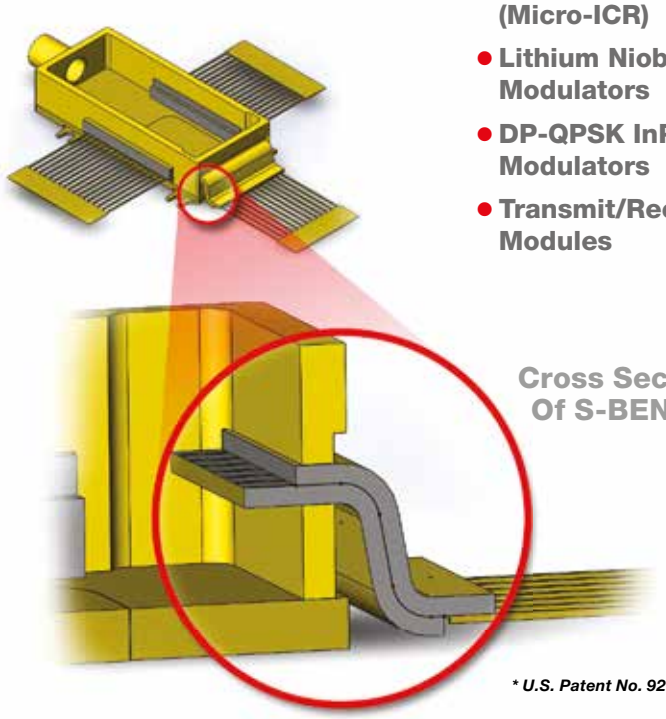
S-Bend
Ceramic Feedthru*

FOR HIGH SPEED TRANSMISSION

- Beta design >50 GHz, insertion loss < 2.5dB, return loss < -15dB
- Smooth uninterrupted RF signal path
- No vias in signal path
- No 90° via transitions
- Reduced reflection coefficient
- Reduced return loss
- Reduced transmission loss
- Increased bandwidth performance

AMETEK's S-Bend Ceramic Feedthru provides a high frequency interconnect advantage by eliminating 90 degree transitions (vertical vias and stair-step vias) used in conventional feedthrough designs. The S-Bend design eliminates the RF reflection caused by 90 degree via transitions. A bandwidth performance increase is achieved as the result of the reduced reflection coefficient (no via transitions) and offers the related benefits of reduced return loss and reduced transmission loss.

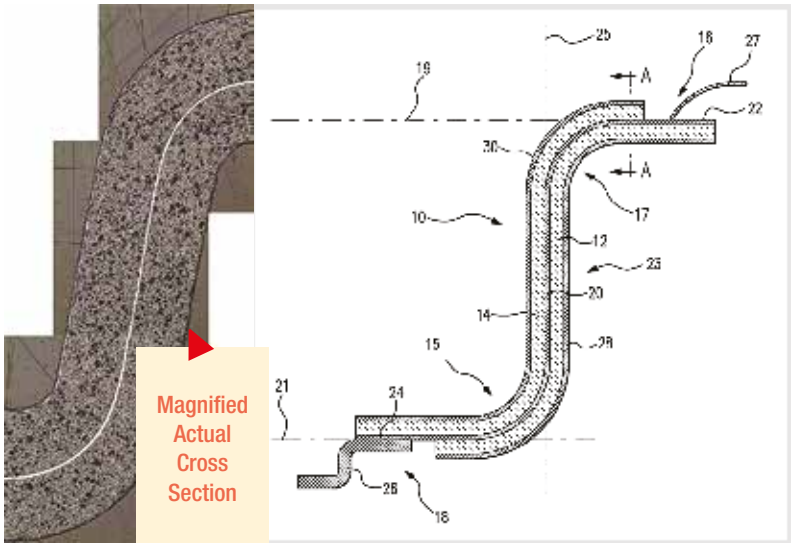
The unique design of the S-Bend Ceramic Feedthru provides a hermetic interconnect solution for high speed application in a structurally robust form factor. The "S" shape provides the critical transition of the RF/ Microwave signal from the wire bond pads inside the package to the output leads on the outside of the package without the use of vias. This design provides an uninterrupted signal path and allows for improved electrical performance without vias, as compared to traditional feedthrough designs.


Cross Section Of S-BEND

** U.S. Patent No. 9277643*

Applications

- Micro-Intradyne Coherent Receivers (Micro-ICR)
- Lithium Niobate Modulators
- DP-QPSK InP Modulators
- Transmit/Receive Modules



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